



OIF To Showcase Record Number of Interoperability Demonstrations at ECOC 2013

Wide Range of Technologies Support Next-Gen 100G and 400G Architectures

Fremont, CA – September 11, 2013 – The Optical Internetworking Forum will host a record number of multi-vendor interoperability demonstrations at [ECOC 2013](#) in London, September 23-25 at the OIF Booth #360. Addressing a wide range of technologies that support 100G and 400G architectures, 11 companies will verify the interoperability of their products in nine separate and diverse demonstrations. The demonstrations will illustrate the feasibility of building and implementing next-generation 100G and 400G capabilities into products today.

OIF Interoperability 2013 – Enabling the Next-Generation of 100G Architectures addresses a variety of OIF supported technologies including: CEI-28G-VSR chip-to-module interfaces for CFP2 and QSFP28 pluggable module form factors, CEI-25G-LR backplane applications, module thermal specifications, and SerDes interconnect solutions.

“The OIF has defined a robust 25G channel technology that the industry is now adopting for 25G, 50G, 100G and 400G applications,” said Ed Frlan of Semtech and the OIF Physical and Link Layer Interoperability Working Group chair. “By showing that the technology interoperates with multiple vendors in hardware that is available today, the industry can now leverage the investments made in 25G technology for future 100G and 400G applications.”

The following companies are participating in the [OIF Interoperability 2013](#): Amphenol, Applied Micro, Cisco, Finisar, Fujitsu Optical Components, Inphi, Molex, MoSys, Semtech, TE Connectivity, and Xilinx. Technologies demonstrated during the testing include host ICs with VSR SerDes capability, host PCB traces, optical module

connectors, high-speed electrical I/O and backplane connectors, module retimers, heat sinks and optical transceivers all operating with 28G electrical interfaces. Agilent Technologies Inc. and Tektronix, Inc. will supply test equipment used in the demonstration.

OIF Leadership to Speak at ECOC 2013

OIF leadership has been invited to speak to ECOC attendees on OIF activities and work efforts. Both presentations will take place in the [Market Focus Theater](#) on the show floor.

- *“Evolution of System Electrical Interfaces Towards 400G Transport”*
Monday, September 23rd at 1:55 – 2:25 pm
Ed Frlan, Semtech, and the OIF PLL Interoperability Working Group chair
Nathan Tracy, TE Connectivity and the OIF Technical Committee vice chair
- *“Requirements and Technologies for Transport SDN”*
Tuesday, Sept. 24th at 1:15 – 1:45 pm
Vishnu Shukla, Verizon, and the OIF president
Hans-Martin Foisel, Deutsche Telekom, and the OIF Carrier Working Group chair and board member

About the OIF

Launched in 1998, the OIF is the first industry group to unite representatives from data and optical networking disciplines, including many of the world's leading carriers, component manufacturers and system vendors. The OIF promotes the development and deployment of interoperable networking solutions and services through the creation of Implementation Agreements (IAs) for optical, interconnect, network processing, component and networking systems technologies. The OIF actively supports and extends the work of standards bodies and industry forums with the goal of promoting worldwide compatibility of optical internetworking products. Information on the OIF can be found at <http://www.oiforum.com>.